

LEADED

BGA SOLDER PASTE

● ● ●
Sn63/Pb37

Melting point 183°C



Product Usage

● ● ●
TIN PASTE

Type number	BST-503-JP
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	70g
size	1.41*1.28 in



Sn63/Pb37

Melting point at medium temperature

183°C



Low residue



Solder spot bright



Rapid welding

Welding requirements for a wide range of products



**SMT
patch**



**LED
patch**



**BGA
welding**



Product List

G.W.:70g

